

Application Number 10/730,878  
Responsive to Office Action mailed July 18, 2006

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OCT 18 2006

**AMENDMENTS TO THE CLAIMS**

This listing of claims will replace all prior versions and listings of claims in the application.

**Listing of Claims:**

**Claim 1 (Previously Presented):** An implantable medical device comprising:  
at least two interconnected modules, each of the modules comprising a respective one of  
at least two housings; and  
an overmold that at least partially encapsulates each of the housings, the overmold  
comprising a lead connection module configured to accept an external lead.

**Claim 2 (Original):** The implantable medical device of claim 1, wherein at least one module  
comprises a control module containing electronic components.

**Claim 3 (Original):** The implantable medical device of claim 1, wherein the overmold  
comprises a first material and a second material, and the lead connection module is deployed  
within the first material.

**Claim 4 (Original):** The implantable medical device of claim 3, wherein the first material  
comprises a non-elastomeric material.

**Claim 5 (Original):** The implantable medical device of claim 1, the lead connection module  
comprising at least one feed-through wire to electrically couple an external lead to an electronic  
component within the implantable medical device.

**Claim 6 (Original):** The implantable medical device of claim 1, wherein the lead connection  
module includes a mechanical lead securing mechanism.

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**Claim 7 (Original):** The implantable medical device of claim 6, wherein the mechanical lead securing mechanism comprises a tool-less mechanical lead securing mechanism.

**Claim 8 (Original):** The implantable medical device of claim 1, wherein the implantable medical device has a maximum thickness of between approximately 4 millimeters and approximately 8 millimeters.

**Claim 9 (Previously Presented):** An overmold for a modular implantable medical device that includes a plurality of modules, each of the modules comprising a respective housing, the overmold comprising:

- a first material configured to hold at least part of the housing of one of the modules;
- a second material coupled to the first material; and
- a lead connection module configured to accept an external lead, the lead connection module being deployed within the overmold.

**Claim 10 (Original):** The overmold of claim 9, wherein the first material comprises a non-elastomeric material.

**Claim 11 (Original):** The overmold of claim 9, wherein the second material comprises an elastomeric material.

**Claim 12 (Original):** The overmold of claim 9, wherein the second material comprises silicone.

**Claim 13 (Original):** The overmold of claim 9, wherein the lead connection module is deployed within the first material.

**Claim 14 (Original):** The overmold of claim 9, wherein the lead connection module is configured to receive an iso-diametric external lead.

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**Claim 15 (New):** The implantable medical device of claim 1, wherein the housings are horizontally distributed at respective locations of the overmold, and separately encapsulated by the overmold.

**Claim 16 (New):** An implantable medical device comprising:

at least two interconnected modules, each of the modules comprising a respective one of at least two housings; and

an overmold that partially encapsulates each of the housings and defines a frame configured to fix a position of the at least two interconnected modules relative to one another, the overmold comprising a lead connection module configured to accept an external lead.

**Claim 17 (New):** The implantable medical device of claim 16, wherein the overmold comprises an non-elastomeric material.

**Claim 18 (New):** The implantable medical device of claim 16, wherein the overmold comprises an elastomeric material.